Rockwell Collins Strategies For STEP

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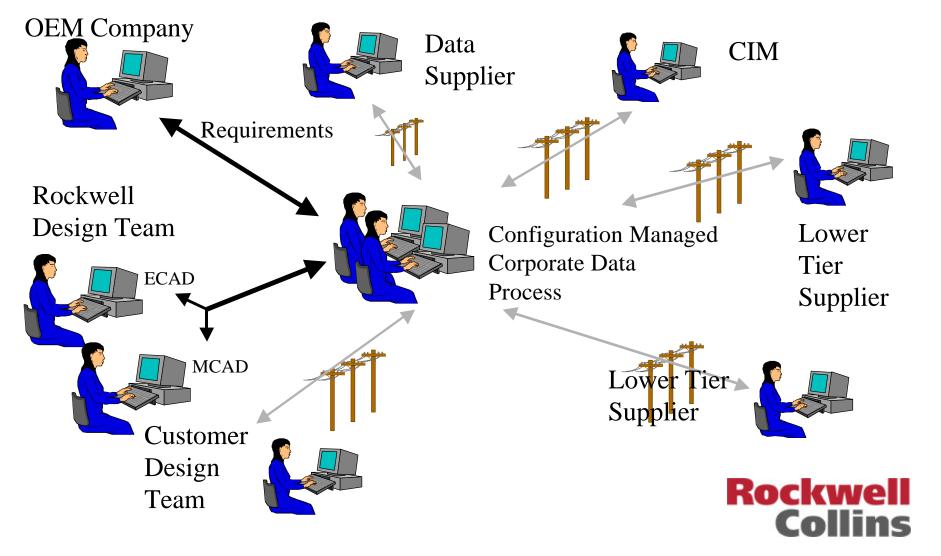
Rockwell Collins Inc.



STEP Usage in Supply Chain



Manufacturing System Simulation



Goals Which STEP Can Help Enable For Rockwell Collins

- Consolidation Of Multiple Proprietary Data Exchange Environments Across Collins
- Provide Standard Data Environment For All Engineering Data, Internal Or External
 - Reduce Effort For Execution Of External Designs Or Builds
 - Provide Common Base For Defining And Exchanging
 Engineering Library Data Regardless Of The Tool Used
- Expand Breadth Of Data Transfer Capability Compared To Current Processes



Where Rockwell Collins Is Now

- A Pilot Program Is In Place For Using AP 203 Data For Some Of Our Mechanical Suppliers
- We Are Developing an AP 210 Output To Pass Electronic Component Library Data To Our CIM Environment
- We Are Developing an AP 210 Output For Passing Product Data From Engineering To CIM
- We are working with Georgia Tech for analysis of PCB products using AP 210 as the interface.



Where Rockwell Collins is Now

- A Joint Effort in Place to Develop a STEP AP210
 Translator For Zuken-Redac Visula Layout System
- Working with The Boeing Company to Identify the Proprietary Issues that Need To Be Resolved When Including Library-Based Data In A STEP File
- Working on the PDES Inc. Electro-mechanical Pilot



Summary For Rockwell Collins

- We Are Optimistic About The Opportunities STEP presents
- We've Are Initiating Activities To Make Use Of STEP
- We've Just Started. It Will Be An Evolution With A Lot Of Work

